

SG 2/7/03

L Number	Hits	Search Text	DB	Time stamp
1	2192	438/108.ccls. or 438/118.ccls. or 438/119.ccls. or 438/124.ccls. or 438/126.ccls. or 438/127.ccls.	USPAT	2003/02/07 13:29
2	830	438/106.ccls.	USPAT	2003/02/07 13:35
-	9	flip adj chip adj bonding adj apparatus	USPAT	2002/08/04 17:49
-	3963	murakami.in.	USPAT	2002/08/04 17:51
-	63	murakami.in. and NEC	USPAT	2002/08/04 18:02
-	243	((flip adj chip) or (flip-chip)) and (pool or pools reservoir or reservoir or (resin adj pool))	USPAT	2002/08/04 18:07
-	0	((flip adj chip) or (flip-chip)) near (reservoir or reservoir or (resin adj pool))	USPAT	2002/08/04 18:08
-	180	((flip adj chip) or (flip-chip)) and (reservoir or reservoir or (resin adj pool))	USPAT	2002/08/05 12:49
-	1979	438/108.ccls. or 438/118.ccls. or 438/119.ccls. or 438/124.ccls. or 438/126.ccls. or 438/127.ccls.	USPAT	2003/02/07 13:27
-	722	438/106.ccls.	USPAT	2003/02/07 13:34
-	291	438/106.ccls. and (438/108.ccls. or 438/118.ccls. or 438/119.ccls. or 438/124.ccls. or 438/126.ccls. or 438/127.ccls.)	USPAT	2002/08/05 13:58
-	2410	438/106.ccls. or (438/108.ccls. or 438/118.ccls. or 438/119.ccls. or 438/124.ccls. or 438/126.ccls. or 438/127.ccls.)	USPAT	2002/08/05 13:58
-	470	(438/106.ccls. or (438/108.ccls. or 438/118.ccls. or 438/119.ccls. or 438/124.ccls. or 438/126.ccls. or 438/127.ccls.)) and ((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))	USPAT	2002/08/05 14:00
-	152	((438/106.ccls. or (438/108.ccls. or 438/118.ccls. or 438/119.ccls. or 438/124.ccls. or 438/126.ccls. or 438/127.ccls.)) and ((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))) and (flip adj chip)	USPAT	2002/08/05 14:00
-	97382	((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))	USPAT	2002/08/05 14:01
-	763	((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))) and ((flip-chip) or (flip adj chip))	USPAT	2002/08/05 14:01
-	124931	((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 14:01
-	785	((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))) and ((flip adj chip) or (flip-chip))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 14:03
-	137	((encapsul\$5 or resin or paste or goop or adhesive or polymer) with (pool or reservoir or cup or well))) and (resin adj pool)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 14:33
-	1688	(438/108.ccls. or 438/118.ccls. or 438/119.ccls. or 438/124.ccls. or 438/126.ccls. or 438/127.ccls.) not 438/106.ccls.	USPAT	2002/08/05 15:25
-	459	((438/108.ccls. or 438/118.ccls. or 438/119.ccls. or 438/124.ccls. or 438/126.ccls. or 438/127.ccls.) not 438/106.ccls.) and (flip adj chip)	USPAT	2002/08/05 15:38
-	0	(flip adj chip) near (dip or dipped or dipping or dips)	USPAT	2002/08/05 15:39

-	0	(flip adj chip) near (dip\$5)	USPAT	2002/08/05 15:39
-	34	(flip adj chip) with (dip or dipped or dipping or dips)	USPAT	2002/08/05 15:39